

Intel Platform Memory Operations

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DDR4 LRDIMM System-Level Validation Results on Intel® Xeon® E7-8800/4800 v4 Processor Family

Listed below are the results from a small sample of DDR4 LRDIMMs tested on Intel® Xeon® E7-8800/4800 v4 processor family.

We are providing this information as a guide to module compatibility with Intel server reference platforms. This testing is not intended to replace the normal OEM qualification process. For results on Intel® motherboards or OEM specific production motherboards, please refer to the OEM's list of qualified memory suppliers. All parts are recommended to be run, using latest Intel® platform Reference Code Production Version.

Updated /May 10th, 2017

LRDIMM QR/8R DDR4- 1:1 Mode 1866 1.2V 1DIMM and 2DIMMs per channel; 2 slots or 3 slots per channel; 4 channels LRDIMM QR: 1600 1.2V 3DIMMs per channel; 3 slots per channel; 4 channels LRDIMM 8R: 1333 1.2V 3DIMMs per channel; 3 slots per channel; 4 channels												
DIMM					DRAM					Buffer		
Supplier	Part Number	Size	CL	Raw Card	Supplier	Part Number	Density Die	Width	Date Code	Vendor	Revision	Note
Micron	MTA72ASS8G72LZ-2G3B2	64GB	17	E2	Micron	MT40A4G4NRE-083E:B	8Gb	x4	1629	IDT	C0	1
Micron	MTA72ASS8G72LZ-2G3B2	64GB	17	E2	Micron	MT40A4G4NRE-083E:B	8Gb	x4	1629	Montage	C0	1
Samsung	M386A4G40DM1-CRC	32GB	17	D1	Samsung	K4A8G045WD-MCRC	4Gb	x4	1545	IDT	A3	1
Samsung	M386A4G40DM1-CRC	32GB	17	D1	Samsung	K4A8G045WD-MCRC	4Gb	x4	1545	Montage	B0	1
Samsung	M386A8K40BM1-CRC	64GB	17	D1	Samsung	K4AAG045WB-MCRC	8Gb	x4	1601	IDT	A3	1
Samsung	M386A8K40BM1-CRC	64GB	17	D1	Samsung	K4AAG045WB-MCRC	8Gb	x4	1601	Montage	B0	1
Samsung	M386AAK40B40-CUC	128GB	20	A0	Samsung	K4ABG045WB-4CUC	8Gb	x4	1603	IDT	A3	1
Samsung	M386AAK40B40-CUC	128GB	20	A0	Samsung	K4ABG045WB-4CUC	8Gb	x4	1603	Montage	B0	1
SK hynix	HMA84GL7AMR4N-UHTE	32GB	17	D1	SK hynix	H5AN8G4NAMR-UHC	4Gb	x4	1548	IDT	A3	1
SK hynix	HMA84GL7AMR4N-UHT2	32GB	17	D1	SK hynix	H5AN8G4NAMR-UHC	4Gb	x4	1548	Montage	B0	1
SK hynix	HMABAGL7M4R4N-UL TE	128GB	20	B	SK hynix	H5ANBG4TM4R-ULC	8Gb	x4	1606	IDT	A3	1
SK hynix	HMABAGL7M4R4N-UL T2	128GB	20	B	SK hynix	H5ANBG4TM4R-ULC	8Gb	x4	1607	Montage	B0	1
SK hynix	HMAA8GL7MMR4N-UHTE	64GB	17	E1	SK hynix	H5ANAG4NMMR-UHC	8Gb	x4	1548	IDT	A3	1
SK hynix	HMAA8GL7MMR4N-UHT2	64GB	17	E1	SK hynix	H5ANAG4NMMR-UHC	8Gb	x4	1550	Montage	B0	1
LRDIMM QR/8R DDR4- 2:1 Mode 1600 1.2V 1DIMM and 2DIMMs per channel; 2 slots or 3 slots per channel; 4 channels LRDIMM QR: 1600 1.2V 3DIMMs per channel; 3 slots per channel; 4 channels LRDIMM 8R: 1333 1.2V 3DIMMs per channel; 3 slots per channel; 4 channels												
DIMM					DRAM					Buffer		
Supplier	Part Number	Size	CL	Raw Card	Supplier	Part Number	Density Die	Width	Date Code	Vendor	Revision	Note
Micron	MTA72ASS8G72LZ-2G3B2	64GB	17	E2	Micron	MT40A4G4NRE-083E:B	8Gb	x4	1629	IDT	C0	1
Micron	MTA72ASS8G72LZ-2G3B2	64GB	17	E2	Micron	MT40A4G4NRE-083E:B	8Gb	x4	1629	Montage	C0	1
Samsung	M386A4G40DM1-CRC	32GB	17	D1	Samsung	K4A8G045WD-MCRC	4Gb	x4	1545	IDT	A3	1
Samsung	M386A4G40DM1-CRC	32GB	17	D1	Samsung	K4A8G045WD-MCRC	4Gb	x4	1545	Montage	B0	1

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Samsung	M386A8K40BM1-CRC	64GB	17	D1	Samsung	K4AAG045WB-MCRC	8Gb	x4	1601	IDT	A3	1
Samsung	M386A8K40BM1-CRC	64GB	17	D1	Samsung	K4AAG045WB-MCRC	8Gb	x4	1601	Montage	B0	1
Samsung	M386AAK40B40-CUC	128GB	20	A0	Samsung	K4ABG045WB-4CUC	8Gb	x4	1603	IDT	A3	1
Samsung	M386AAK40B40-CUC	128GB	20	A0	Samsung	K4ABG045WB-4CUC	8Gb	x4	1603	Montage	B0	1

LRDIMM QR/8R DDR4- 2:1 Mode
1600 1.2V 1DIMM and 2DIMMs per channel; 2 slots or 3 slots per channel; 4 channels
LRDIMM QR: 1600 1.2V 3DIMMs per channel; 3 slots per channel; 4 channels
LRDIMM 8R: 1333 1.2V 3DIMMs per channel; 3 slots per channel; 4 channels

DIMM					DRAM					Buffer		
Supplier	Part Number	Size	CL	Raw Card	Supplier	Part Number	Density Die	Width	Date Code	Vendor	Revision	Note
SK hynix	HMA84GL7AMR4N-UHTE	32GB	17	D1	SK hynix	H5AN8G4NAMR-UHC	4Gb	x4	1548	IDT	A3	1
SK hynix	HMA84GL7AMR4N-UHT2	32GB	17	D1	SK hynix	H5AN8G4NAMR-UHC	4Gb	x4	1548	Montage	B0	1
SK hynix	HMABAGL7M4R4N-UL TE	128GB	20	B	SK hynix	H5ANBG4TM4R-ULC	8Gb	x4	1606	IDT	A3	1
SK hynix	HMABAGL7M4R4N-UL T2	128GB	20	B	SK hynix	H5ANBG4TM4R-ULC	8Gb	x4	1607	Montage	B0	1
SK hynix	HMAA8GL7MMR4N-UHTE	64GB	17	E1	SK hynix	H5ANAG4NMMR-UHC	8Gb	x4	1548	IDT	A3	1
SK hynix	HMAA8GL7MMR4N-UHT2	64GB	17	E1	SK hynix	H5ANAG4NMMR-UHC	8Gb	x4	1550	Montage	B0	1

1. All 32GB / 64GB LRDIMM parts are DDP (Dual Die package); all 128GB LRDIMM are 8R, 3DS-TSV technology.

